

METHOD OF PREPARING WHOLE SEMICONDUCTOR WAFER FOR ANALYSIS

Abstract of Disclosure

A method for preparing a semiconductor wafer for whole wafer backside inspection is disclosed. The frontside of the wafer is covered with a protective frontside substrate and the backside portion of the wafer is thinned using conventional techniques. The whole wafer backside is then polished and a backside substrate, preferably of transparent material is juxtaposed to the backside of the wafer, such as with an adhesive or with a frame. The frontside substrate is then removed, exposing electronic devices for device inspection. The backside of the wafer is maintained open or available to backside inspection such as emission microscopy techniques used to detect defects which emit light.

Figures